

EV Group and Dymek Company form joint venture company in Malaysia – May 23, 2023



Tech News

imec first to demonstrate conductor films on 300mm wafers with lower resistivity than Cu and Ru

This week, at the 2023 IEEE International Interconnect Technology Conference (2023 IEEE IITC), imec provides the first experimental evidence that the resistivity of a thin conductor film on a 300mm Si wafer can be lower than that of Cu and Ru, which are currently used in interconnect metallization schemes. More>>



NVIDIA collaborates with Microsoft to accelerate enterprise-ready generative AI

NVIDIA today announced that it is integrating its NVIDIA AI Enterprise software into Microsoft's Azure Machine Learning to help enterprises accelerate their AI initiatives. More>>



FEATURED PRODUCT

Efficient Vacuum for Load Lock and Transfer Chambers Busch TORRI BD 600 multi-stage rotary lobe vacuum pumps.

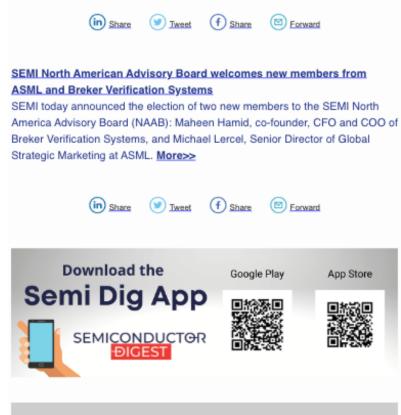
- · Fast pump-down time
- · Compact space-saving size
- · Low energy consumption

Learn more



Business News

EV Group and Dymek Company form joint venture company in Malaysia EV Group and Dymek Company today announced that they have established a new joint venture company in Malaysia. <u>More>></u>



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